

**60V DUAL N-CHANNEL ENHANCEMENT MODE MOSFET**
**Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub>	I <sub>D</sub> T <sub>A</sub> = +25°C
60V	66mΩ @ V <sub>GS</sub> = 10V	4.4A
	97mΩ @ V <sub>GS</sub> = 4.5V	3.6A

**Description and Applications**

This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

- Motor controls
- Backlighting
- DC-DC converters
- Power-management functions

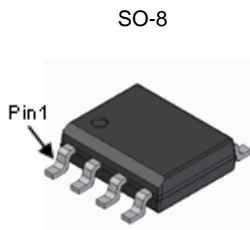
**Features and Benefits**

- Low On-Resistance
- Fast Switching Speed
- 100% Unclamped Inductive Switch (UIS) Test in Production
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **The DMN6066SSDQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.**

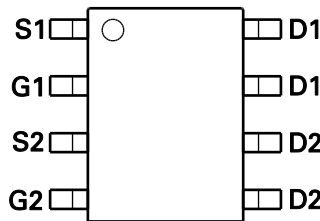
<https://www.diodes.com/quality/product-definitions/>

**Mechanical Data**

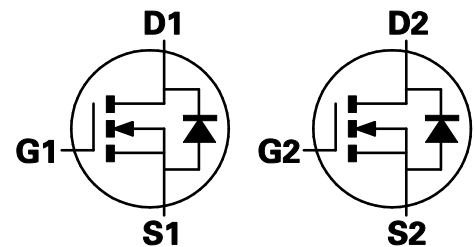
- Package: SO-8
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See Diagram Below
- Terminals: Finish – Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (E3)
- Weight: 0.074 grams (Approximate)



Top View



Top View

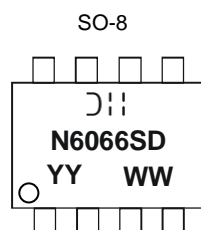


Equivalent Circuit

**Ordering Information** (Note 4)

Orderable Part Number	Package	Packing	
		Qty.	Carrier
DMN6066SSDQ-13	SO-8	2,500	Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
  2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

**Marking Information**


☺☺☺ = Manufacturer's Marking  
 N6066SD = Product Type Marking Code  
 YYWW = Date Code Marking  
 YY = Year (ex: 24 = 2024)  
 WW = Week (01 to 53)

### Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

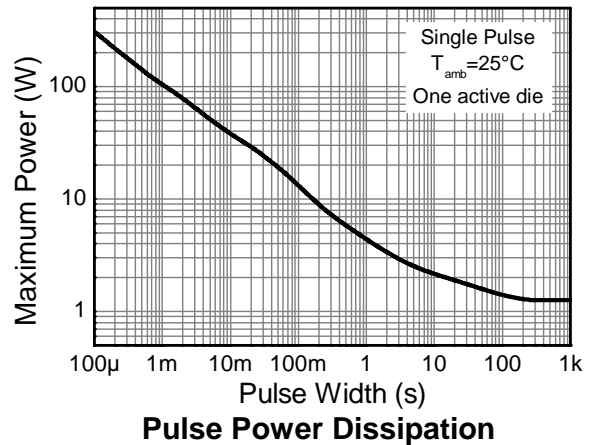
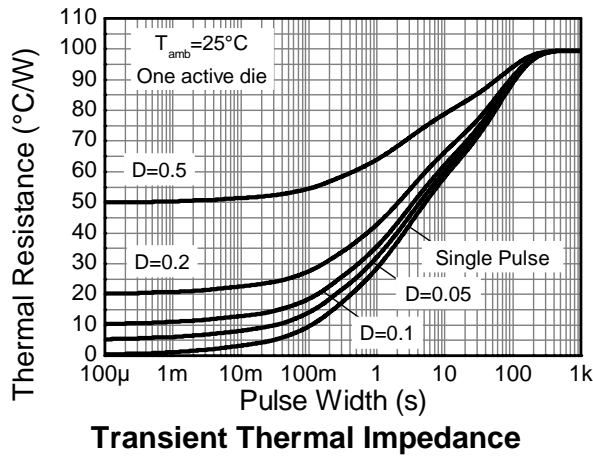
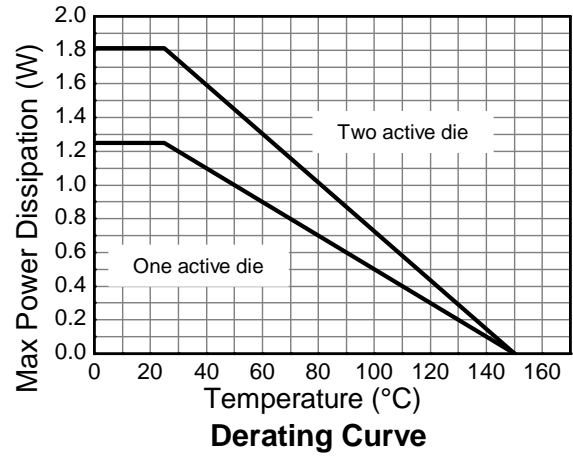
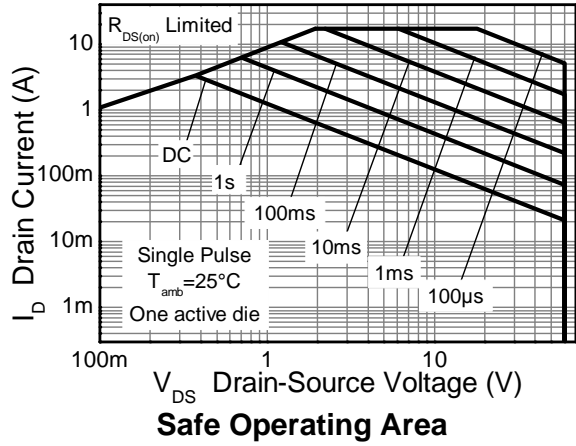
Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V <sub>DSS</sub>	60	V
Gate-Source Voltage	(Note 5)	V <sub>GS</sub>	±20	V
Single Pulsed Avalanche Energy		E <sub>AS</sub>	37.5	mJ
Single Pulsed Avalanche Current		I <sub>AS</sub>	5.0	A
Continuous Drain Current	V <sub>GS</sub> = 10V	(Note 8)	4.4	A
		T <sub>A</sub> = +70°C (Note 8)	3.5	
		(Note 6)	3.3	
Pulsed Drain Current	V <sub>GS</sub> = 10V	I <sub>DM</sub>	17.0	A
Continuous Source Current (Body Diode)		I <sub>S</sub>	3.2	A
Pulsed Source Current (Body Diode)		I <sub>SM</sub>	17.0	A

### Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Power Dissipation Linear Derating Factor	(Notes 6 & 9)	P <sub>D</sub>	1.25	W mW/°C
			10	
	(Notes 6 & 10)		1.8	
			14.3	
Thermal Resistance, Junction to Ambient	(Notes 7 & 9)	R <sub>θJA</sub>	2.14	°C/W
			17.2	
	(Notes 6 & 9)		100	
	(Notes 6 & 10)		70	
Thermal Resistance, Junction to Lead	(Notes 7 & 9)	R <sub>θJL</sub>	58	°C/W
	(Notes 9 & 11)		55	
Operating and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

- Notes:
5. AEC-Q101 V<sub>GS</sub> maximum is ±16V.
  6. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
  7. Same as Note 6, except the device is measured at t ≤ 10 sec.
  8. Same as Note 6, except the device is pulsed with D = 0.02 and pulse width 300µs. The pulse current is limited by the maximum junction temperature.
  9. For a dual device with one active die.
  10. For a device with two active dies running at equal power.
  11. Thermal resistance from junction to solder-point (at the end of the drain lead).
  12. UIS in production with L = 3.0mH, I<sub>AS</sub> = 5.0A, R<sub>G</sub> = 25Ω, V<sub>DD</sub> = 50V, starting T<sub>J</sub> = +25°C.

**Thermal Characteristics**

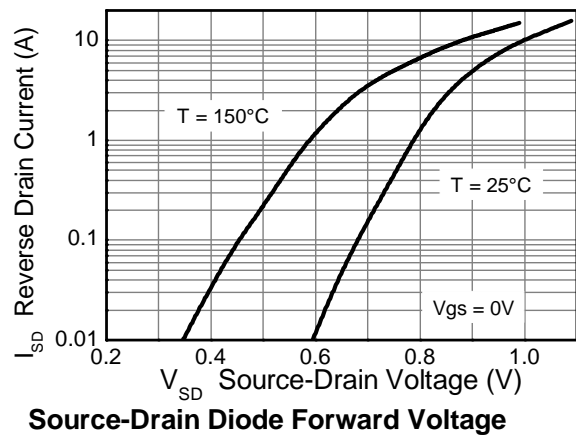
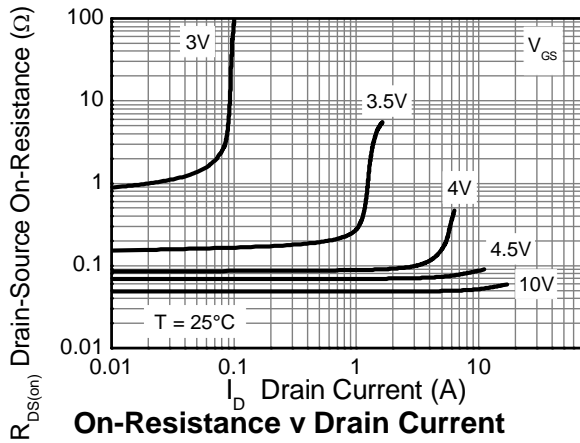
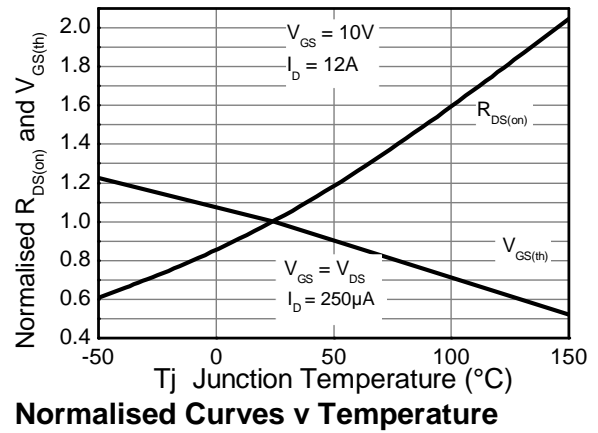
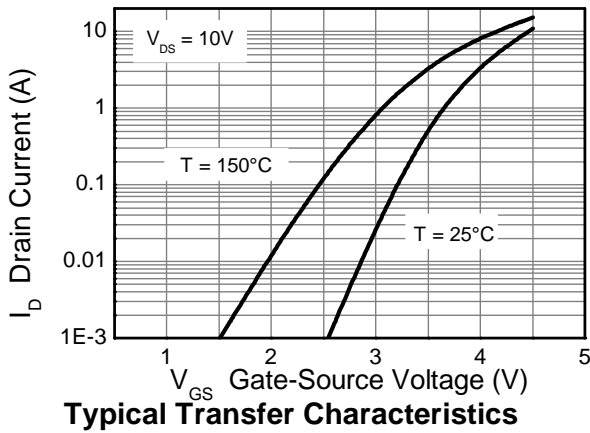
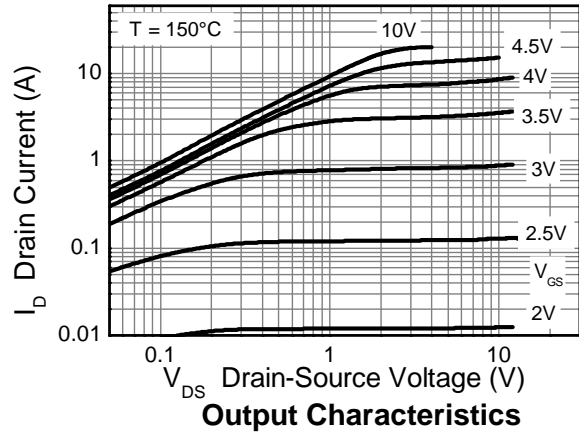
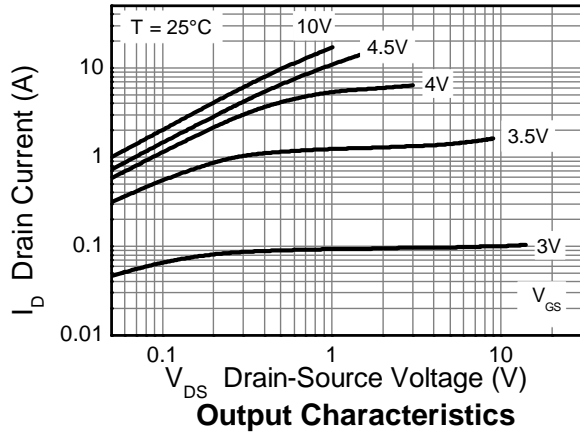


**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

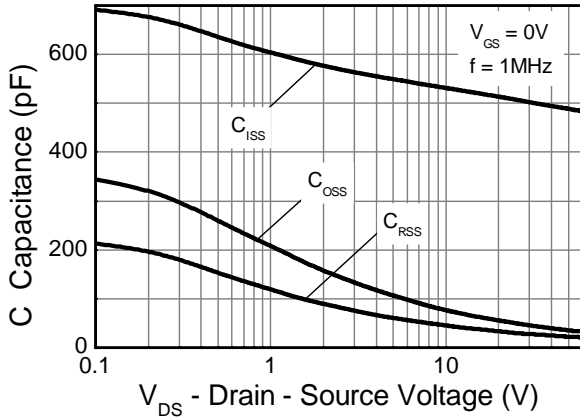
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	60	—	—	V	I <sub>D</sub> = 250μA, V <sub>GS</sub> = 0V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	—	—	0.5	μA	V <sub>DS</sub> = 60V, V <sub>GS</sub> = 0V
Gate-Source Leakage	I <sub>GSS</sub>	—	—	±100	nA	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	1.0	—	3.0	V	I <sub>D</sub> = 250μA, V <sub>DS</sub> = V <sub>GS</sub>
Static Drain-Source On-Resistance (Note 13)	R <sub>DS(on)</sub>	—	48	66	mΩ	V <sub>GS</sub> = 10V, I <sub>D</sub> = 4.5A
			68	97		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 3.5A
Forward Transconductance (Notes 13 & 14)	g <sub>fs</sub>	—	19.2	—	S	V <sub>DS</sub> = 15V, I <sub>D</sub> = 6A
Diode Forward Voltage (Note 13)	V <sub>SD</sub>	—	0.89	1.15	V	I <sub>S</sub> = 4.5A, V <sub>GS</sub> = 0V
Reverse-Recovery Time (Note 14)	t <sub>rr</sub>	—	22.2	—	ns	I <sub>S</sub> = 1.9A, di/dt = 100A/μs
Reverse-Recovery Charge (Note 14)	Q <sub>rr</sub>	—	16.9	—	nC	
<b>DYNAMIC CHARACTERISTICS (Note 14)</b>						
Input Capacitance	C <sub>iss</sub>	—	502	—	pF	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V f = 1MHz
Output Capacitance	C <sub>oss</sub>	—	45.7	—	pF	
Reverse Transfer Capacitance	C <sub>rss</sub>	—	27.1	—	pF	
Total Gate Charge (Note 15)	Q <sub>g</sub>	—	5.4	—	nC	V <sub>GS</sub> = 4.5V
Total Gate Charge (Note 15)	Q <sub>g</sub>	—	10.3	—	nC	V <sub>GS</sub> = 10V V <sub>DS</sub> = 30V I <sub>D</sub> = 4.5A
Gate-Source Charge (Note 15)	Q <sub>gs</sub>	—	1.7	—	nC	
Gate-Drain Charge (Note 15)	Q <sub>gd</sub>	—	3.2	—	nC	
Turn-On Delay Time (Note 15)	t <sub>D(on)</sub>	—	2.7	—	ns	V <sub>DD</sub> = 30V, V <sub>GS</sub> = 10V I <sub>D</sub> = 1A, R <sub>G</sub> ≅ 6.0Ω
Turn-On Rise Time (Note 15)	t <sub>r</sub>	—	2.4	—	ns	
Turn-Off Delay Time (Note 15)	t <sub>D(off)</sub>	—	14.7	—	ns	
Turn-Off Fall Time (Note 15)	t <sub>f</sub>	—	5.4	—	ns	

- Notes:
- 13. Measured under pulsed conditions. Pulse width ≤ 300μs; duty cycle ≤ 2%.
  - 14. For design aid only, not subject to production testing.
  - 15. Switching characteristics are independent of operating junction temperatures.

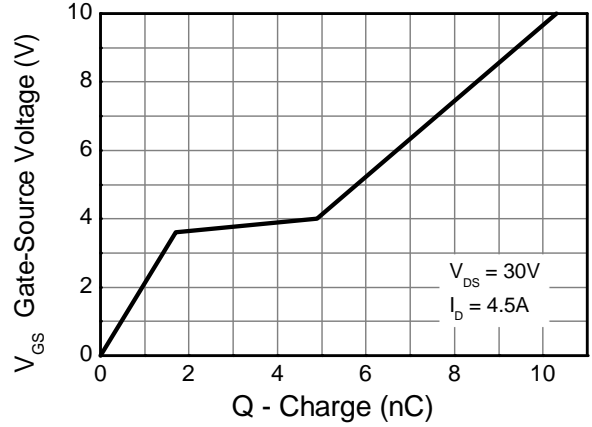
**Typical Characteristics**



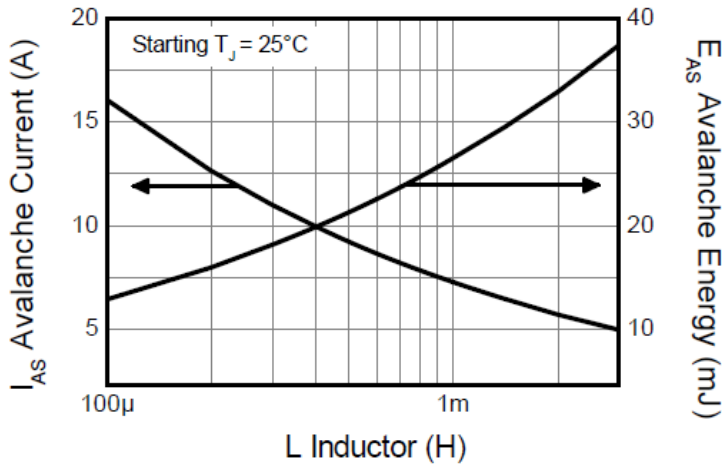
**Typical Characteristics** (continued)



**Capacitance v Drain-Source Voltage**

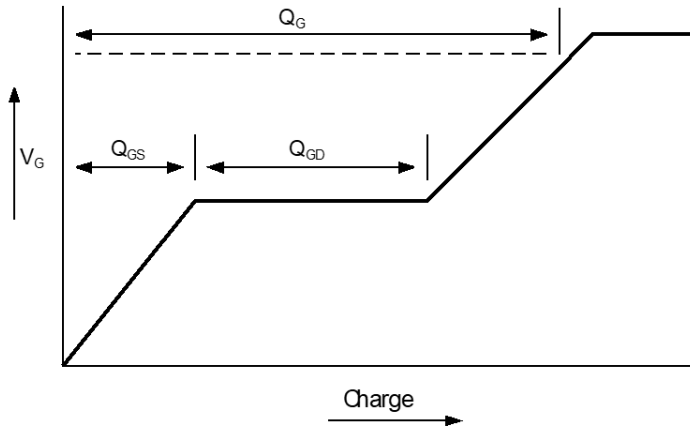


**Gate-Source Voltage v Gate Charge**

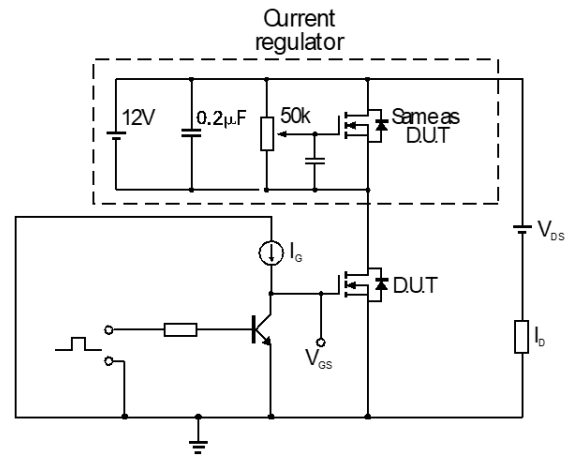


**Single-Pulsed Avalanche Rating**

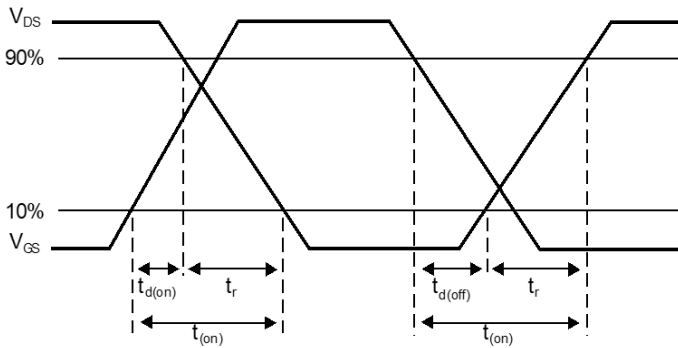
**Test Circuits**



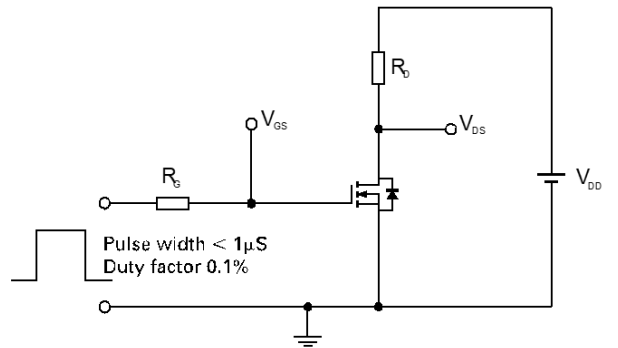
**Basic gate charge waveform**



**Gate charge test circuit**



**Switching time waveforms**

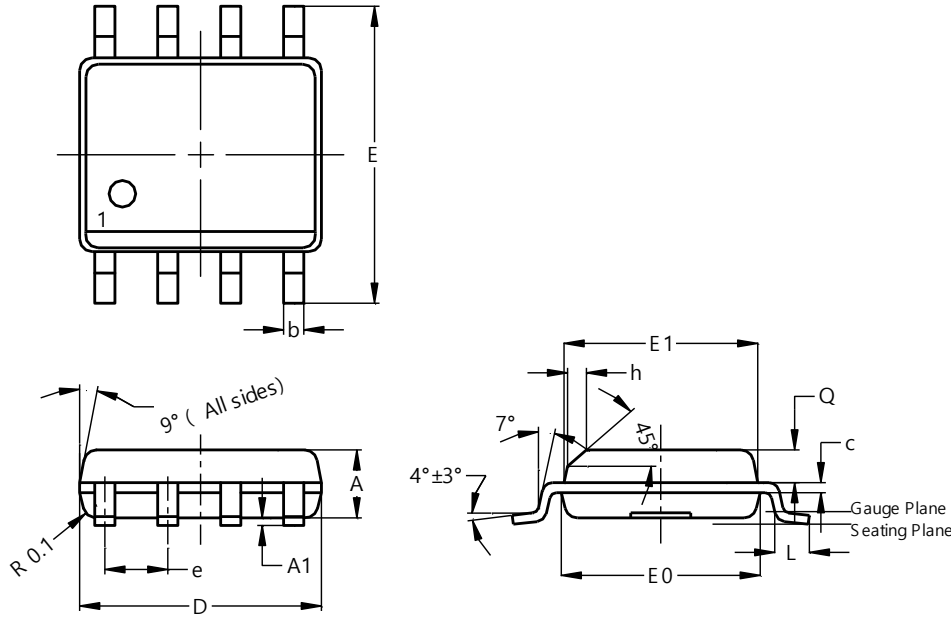


**Switching time test circuit**

**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SO-8

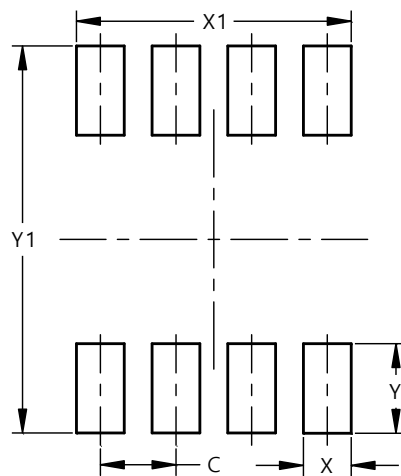


SO-8			
Dim	Min	Max	Typ
A	1.40	1.50	1.45
A1	0.10	0.20	0.15
b	0.30	0.50	0.40
c	0.15	0.25	0.20
D	4.85	4.95	4.90
E	5.90	6.10	6.00
E1	3.80	3.90	3.85
E0	3.85	3.95	3.90
e	--	--	1.27
h	--	--	0.35
L	0.62	0.82	0.72
Q	0.60	0.70	0.65
<b>All Dimensions in mm</b>			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SO-8



Dimensions	Value (in mm)
C	1.27
X	0.802
X1	4.612
Y	1.505
Y1	6.50



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